

ELECTRONICS INDIA CIRCUITS PVT. LTD.



www.electronicsindiapune.com





ELECTRONICS INDIA CIRCUITS PVT LTD formerly known ELECTRONICS INDAI is a well managed organization in India, established in 1996, engaged in manufacturing of professional grade Printed Circuits Boards in SINGLE SIDE, DOUBLE SIDE & MULTILAYER PCB 4L to 32L.

We do MULTILAYER under name of EIPRISM CIRCUITRONICS LLP.



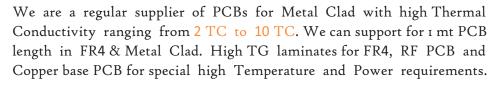
We are a One Stop Solution with advance production facilities with capacity of Single Side 25K sq mts/month, Double Side 3K Sq mts/month & Multilayer 1.5K Sq mts/month in factory built up area of 80k sq ft. for high quality Printed Circuit Boards (PCBs).

We Concentrate on a specific portfolio of technology with special application for Automotive, Instrumentation, Telecommunication & Defence segment. We can support for Proto, Small, Medium and high Volume production requirements. We are specialize in supporting Express deliveries and Quick turn requirements.



We are ISO90012015 & IATF 16949:2016 certified.

We have an experienced team to support customer technical requirements from 4 to 32 Layers with Impedance controlled board, 4/4 mil Trace/Space with 6/12 Drill/Pad.





We proudly claim to be excellent in quality, scheduled deliveries, and competitive pricing structure.

We are confident of meeting your every need in the Printed Circuit Boards. Please find the attached herewith our company profile...

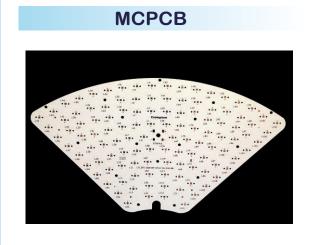


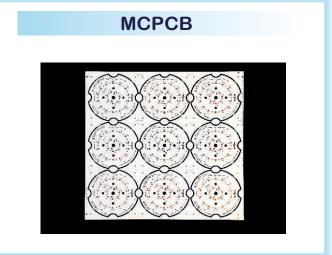


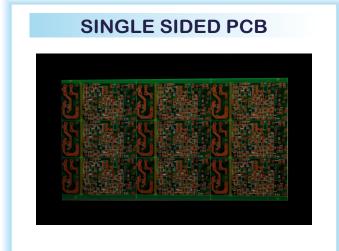


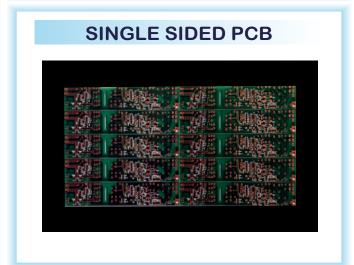


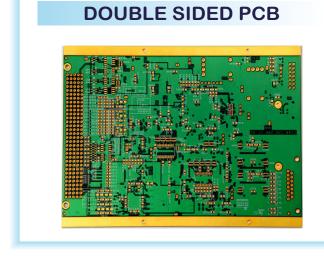














TECHNICAL SPECIFICATION

Sr.No.	PARAMETERS	МСРСВ	SINGLE SIDE	DOUBLE SIDE
1	PCB THICKNESS	0.8 TO 1.6MM	0.8 TO 1.6MM	0.8 TO 3.2MM
2	BASE COPPER	18u-105u	18u-105u	18u-105u
3	MIN HOLE SIZE (DRILL DIA)	1.2MM (48MIL)	0.6MM (24MIL)	0.4MM (16MIL)
4	MIN SIZE OF SLOT	1.5MM (60MIL)	0.8MM (32MIL)	0.8MM (32MIL)
5	MIN ANNULAR RING FOR VIA HOLES OUTER	0.25MM (10MIL)	0.25MM (10MIL)	0.25MM (10MIL)
6	MIN ANNULAR RING FOR COMP. HOLES OUTER	0.30MM (12MIL)	0.30MM (12MIL)	0.30MM (12MIL)
7	MIN OUTER LAYER TRACK / SPACE	0.30/0.30MM	0.30/0.30MM	0.20/0.20MM
8	MIN BOARD EDGE TO COPPER CLEARANCE (ROUTED BOARDS)	0.30MM (12MIL)	0.30MM (12MIL)	0.20MM (8MIL)
9	MIN BOARD EDGE TO COPPER CLEARANCE (SCORED BOARDS)	0.50MM (20MIL)	0.50MM (20MIL)	0.50MM (20MIL)
10	MIN SOLDER MASK CLEARANCE	0.05MM (2MIL)	0.10MM (4MIL)	0.10MM (4MIL)
11	MIN SOLDER MASK WIDTH BETWEEN SMD IC (MIN.DAM)	0.15MM (6MIL)	0.15MM (6MIL)	0.15MM (6MIL)
12	MIN WIDTH OF SILKSCREEN	0.20MM (8MIL)	0.20MM (8MIL)	0.20MM (8MIL)
13	MIN SMD GAP	0.25MM (10MIL)	0.25MM (10MIL)	0.25MM (10MIL)
14	PCB SURFACE FINISH	ENIG / LEADED HASL / LEAD FREE HASL / EMERSON TIN PLATING		
15	SOLDER MASK COLOUR	GREEN, BLUE, RED, WHITE, BLACK		
16	PCB PROFILE	ROUTING / SCORING		

MULTILAYER TECHNICAL SPECIFICATION

Sr.No.	PARAMETERS		STANDARD	CRITICAL	
1	LAYER COUNT		UP TO 12 LAYERS	14-24 LAYERS	
2	PCB THICKNESS		0.8 TO 3.2MM	0.6 TO 4.5MM	
3	MIN I/L CORE THICKNESS		0.10MM (4MIL)	0.075MM (3MIL)	
4	MIN HOLE SIZE (DRILL DIA)		0.4MM (16MIL)	0.25MM (10MIL)	
5	MIN SIZE OF PTH SLOT		0.80MM	0.60MM	
6	MIN ANNULAR RING FOR VIA HOLES (INNER & OUTER)		0.10 - 0.15MM (4-6MIL)	0.075MM (3MIL)	
7	MIN ANNULAR RING FOR COMP. HOLES (INNER & OUTER)		0.15MM (6MIL)	0.10MM (4MIL)	
		18/18u BASE COPPER	0.15/0.15MM (6/6MIL) 0.10/0.10MM (4/4MIL)		
	MIN INNER LAYER TRACK/SPACE	35/35u BASE COPPER	0.20/0.20MM (8/8MIL)	0.13/0.13MM (5/5MIL)	
9		70/70u BASE COPPER	0.25/0.25MM (10/10MIL)	0.20/0.20MM (8/8MIL)	
		105/105u BASE COPPER	0.35/0.35MM (14/14MIL)	0.30/0.30MM (12/12MIL)	
	MIN INNER LAYER ANTIPAD (DRILL TO PAD ISOLATION)	4-6 LAYERS	0.35MM (14MIL)	0.20MM (8MIL)	
10		8-10 LAYERS	0.40MM (16MIL)	0.20MM (8MIL)	
		10-24 LAYERS	0.50MM (20MIL)	0.25MM (10MIL)	
11	MIN BOARD EDGE TO COPPER CLEARANCE (ROUTED BOARDS)		0.15MM (6MIL)	0.10MM (4MIL)	
12	MIN BOARD EDGE TO COPPER CLEARANCE (SCORED BOARDS)		0.35MM (14MIL)	0.30MM (12MIN)	
13	MIN SOLDER MASK CLEARANCE		0.05MM (2MIL)	0.038MM (1.5MIL)	
14	MIN SOLDER MASK WIDTH BETWEEN SMD IC (MIN.DAM)		0.125MM (5MIL)	0.10MM (4MIL)	
15	MIN WIDTH OF SILKSCREEN		0.15MM (6MIL)	0.125MM (5MIL)	
16	MIN SMD PITCH		0.50MM (20MIL)	0.40MM (16MIL)	
17	MIN BGA PITCH		0.60MM (24MIL)	0.40MM (16MIL)	
18	ASPECT RATION (THICKNESS TO DRILL)		4:1	6.4:1	
19	HOLE FILL / CAP PLATE FOR MAX. HOLE SIZE		0.25MM (10MIL)	0.30MM (12MIL)	
20	CONTROLLED IMPEDANCE		TOLL +/- 10%	TOLL +/- 10%	
21	MATERIAL		HITG FR-4 HYDROCARBON CERAMIC	HI TG FR-4 RIGID POLYMIDE FLEX POLYMIDE LOW LOSS HIGH SPEED MATERIAL	
22	DEFAULT STANDARDS		IPC CLASS-2	IPC CLASS-2	
23	I/L BASE Cu		18u-105u		
24	O/L BASE Cu		18u-140u Finished		
25	PCB FINISH		ENIG / LEADED HASL / LEAD FREE HASL / IMMERSION TIN PLATING		
26	PRESS FIT HOLE TOLL		+/- 0.05MM (2MIL)		
27	SOLDER MASK COLOUR		GREEN, BLUE, RED, WHITE, BLACK		
28	PCB PROFILE		ROUTING/SCORING		





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